FLIR PCB Assembly Notes

The following assembly notes shall serve as the master and shall supersede all other notes contained in other files, ODB++ or Gerber, supplied by FLIR for the manufacture of this PCB unless otherwise specified.

Product material and assembly process to be RoHS 2 and REACH-181 compliant in accordance with the European Union Directive on the Restriction and use of Certain Hazardous Substances in Electrical and Electronic Equipment 2011/65/EU, as well as REACH restrictions consistent with Regulation (EC) 1907/2006, per the list of 181 SVHCs (Substances of Very High Concern).

1. ALL IPC SPECIFICATIONS TO BE PER CLASS 2
2. PRIOR TO ASSEMBLY, ASSEMBLER TO VERIFY BARE BOARDS WERE BUILT PER IPC-6012 AND INSPECTED PER IPC-A-600
3. IF ASSEMBLER IS ALSO CONTRACTED TO PROVIDE FABRICATION, PRIOR TO FABRICATION CONFIRM THAT ALL COMPONENT FOOTPRINTS IN GERBER DATA CONFORM TO IPC-7351, OR OBTAIN WAIVER FROM FLIR FOR SPECIFIED COMPONENTS
4. PCB TO BE MANUFACTURED TO IPC-610 WORKMANSHIP AND INSPECTION STANDARDS AND IN ACCORDANCE WITH IPC-J-STD-001D. SOLDER JOINTS TO MEET APPLICABLE SOLERDABILITY TESTS PER IPC-J-STD-003
5. PCB SOLDER ALLOY AND SOLDER PROCESSES TO BE FULLY ROHS COMPLIANT PER IPC-J-STD-006.
6. PCB SOLDER PASTE TO BE ROHS COMPLIANT AND MEET IPC-HDBK-005 AND IPC-J-STD-005
7. PCB SOLDER FLUXES TO BE ROHS COMPLIANT AND MEET IPC-J-STD-004
8. SOLDER REFLOW PROFILES TO BE DESIGNED IN CONSIDERATION OF ROHS COMPLIANCE AND TEMPERATURE LIMITS OF 370HR OR EQUIVALENT MATERIAL, UNLESS OTHERWISE INDICATED OR APPROPRIATE USE SOLDER PROFILE PER IPC/JEDEC J-STD-020C
9. PCB IS STATIC SENSITIVE ASSEMBLY, STATIC ELIMINATING PROCESSES TO BE UTILIZED DURING ASSEMBLY AND HANDLING
10. PCB DELIVERABLE TO BE FULLY ROHS COMPATIBLE AND TO BE MARKED TO INDICATE ROHS COMPLIANCE.
11. REFER TO ACCOMPANYING BOM FOR PARTS NOT DESCRIBED IN THIS DOCUMENT OR PARTS INTENTIONALLY UNINSTALLED
12. COMPONENT PINS 1 IDENTIFIED BY CIRCLE, BEVEL, TRIANGLE, OR RECESSED LINE
13. TEST POINTS AND OTHER ELECTRICAL OR MECHANICAL CONTACT INTERFACES TO BE FREE OF FLUX, RESIDUE, AND CONTAMINATION
14. UNLESS OTHERWISE DIRECTED, AFFIX LABEL IN AREA ADEQUATE FOR ACCESS AND LEGIBILITY. MARKINGS TO INCLUDE THE FOLLOWING:
   A. FLIR PART NUMBER AND REVISION
   B. MANUFACTURING LOT AND SERIAL NUMBER
   C. DATE CODE
   D. TEST-PASS INSPECTION
15. TRIM COMPONENT LEADS WITHIN .062" OF PCB FROM SOLDER SIDE OF PCB IF APPLICABLE.
16. FINISHED PCB PERIMETER TO BE FREE OF ALL BURRS, PITS, MOUSEBITES, AND V-SCORE RESIDUE. FINISHED PCB OUTLINE DIMENSIONS TOLERANCE .127 [.005]. FAILURE TO MEET THIS REQUIREMENT IS SUBJECT TO QA REJECTION.
17. FINISHED ASSEMBLY PCBs MUST BE INDIVIDUALLY BAGGED IN ANTI-STATIC BAGS OR STATIC DISSIPATIVE ESD SHIELDING BAGS

"PROPRIETARY - FLIR Systems Inc."

The information contained herein does not contain technology as defined by EAR, 15 CFR72, is publicly available, and therefore not subject to EAR.

ASSEMBLY
TS BUTNER 10/9/2018
M BROWN 10/9/2018
Lepton Breakout
Top-side View

J2 Installed on far side.

Please see sheet 4 of 4

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Bottom-side View

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"PROPRIETARY - FLIR Systems Inc."